L Number	Hits	Search Text	DB	Time stamp
1	838	(stack$3 near3 (chip die dice wafer semiconductor IC (integrated adj circuit))) and @ad<19990503 and shield$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:44
2	97	(stack$3 near3 (chip die dice wafer semiconductor IC (integrated adj circuit))) and @ad<19990503 and (shield$3 near4 (wall side outside exterior))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:45
-	174	berezny-nema.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 09:53
-	0	berezny-nema.xa.	US-PGPUB	2004/02/17 11:02
-	141078	transmit$4 and receiv$3 and @ad<19990503 and (semiconductor die dice chip IC (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 11:49
-	317	(transmit$4 and receiv$3 and @ad<19990503 and (semiconductor die dice chip IC (integrated adj circuit))) and (chip near3 stack$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 11:51
-	14	((transmit$4 and receiv$3 and @ad<19990503 and (semiconductor die dice chip IC (integrated adj circuit))) and (chip near3 stack$3)) and deactivat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 12:21
-	4	(("5444387") or ("5229647")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 14:48
-	0	tranceiver and @ad<19990503 and (stack$3 near3 (semiconductor die dice chip IC (integrated adj circuit) wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 14:54
-	1190	transmit$4 and receiv$3 and @ad<19990503 and (stack$3 near3 (semiconductor die dice chip IC (integrated adj circuit) wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 14:54
-	486	(transmit$4 and receiv$3 and @ad<19990503 and (stack$3 near3 (semiconductor die dice chip IC (integrated adj circuit) wafer))) and interconnect$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 14:55
-	17	((transmit$4 and receiv$3 and @ad<19990503 and (stack$3 near3 (semiconductor die dice chip IC (integrated adj circuit) wafer))) and interconnect$3) and deactivat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 15:01
-	316	((transmit$4 and receiv$3 and @ad<19990503 and (stack$3 near3 (semiconductor die dice chip IC (integrated adj circuit) wafer))) and interconnect$3) and (test$3 fail$3 bad malfunction$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 17:14

-	1572	((438/109) or (257/777)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 17:14
-	762	(((438/109) or (257/777)).CCLS.) and @ad<19990503	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 17:15
-	83	((((438/109) or (257/777)).CCLS.) and @ad<19990503) and (shield$3 emf emi interference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/17 17:15